

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC057N03LS G	**Issued**	11. April 2021
MA#	MA001823644		
Package	PG-TDSON-8-14	**Weight***	118.84 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.076	0.91	0.91	9058	9058
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		82	
	non noble metal	zinc	7440-66-6	0.039	0.03		327	
	non noble metal	iron	7439-89-6	0.778	0.65		6547	
	non noble metal	copper	7440-50-8	31.590	26.58	27.27	265821	272777
wire	non noble metal	copper	7440-50-8	0.058	0.05	0.05	485	485
encapsulation	organic material	carbon black	1333-86-4	0.240	0.20		2018	
	plastics	epoxy resin	-	7.435	6.26		62560	
	inorganic material	silicondioxide	60676-86-0	40.291	33.91	40.37	339037	403615
leadfinish	non noble metal	tin	7440-31-5	1.243	1.05	1.05	10456	10456
plating	noble metal	silver	7440-22-4	0.037	0.03	0.03	315	315
solder	non noble metal	tin	7440-31-5	0.026	0.02		220	
	noble metal	silver	7440-22-4	0.033	0.03		275	
	non noble metal	lead	7439-92-1	1.250	1.05	1.10	10517	11012
heatspreader	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	zinc	7440-66-6	0.021	0.02		180	
	non noble metal	iron	7439-89-6	0.428	0.36		3598	
	non noble metal	copper	7440-50-8	17.360	14.61	14.99	146079	149902
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			43	
	non noble metal	iron	7439-89-6	0.017	0.01		142	
	non noble metal	copper	7440-50-8	16.898	14.22	14.23	142195	142380
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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